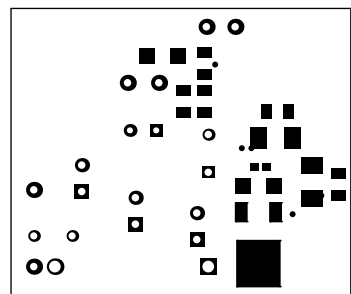
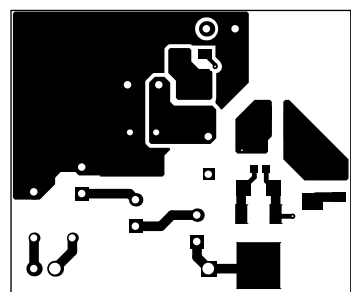


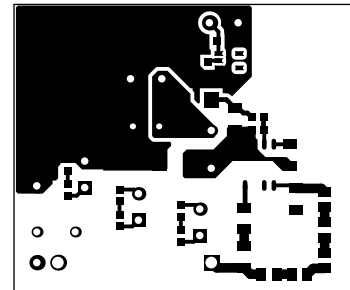
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11302	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Overlay	GENERATED : 10/7/2015 2:55:13 PM	TEXAS INSTRUMENTS	



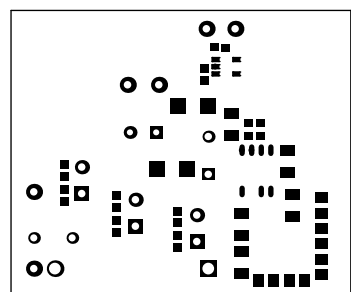
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LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 10/7/2015 2:55:14 PM	TEXAS INSTRUMENTS	



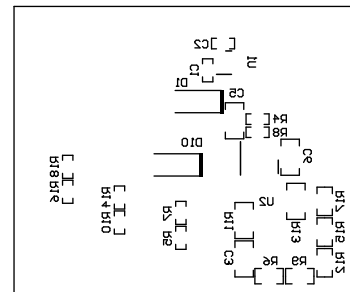
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LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 10/7/2015 2:55:14 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11302	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 10/7/2015 2:55:15 PM	TEXAS INSTRUMENTS	

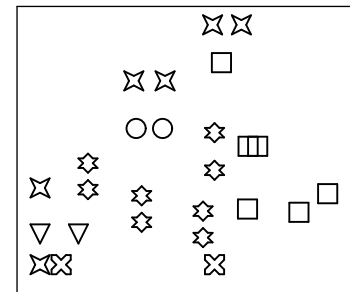


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11302	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/7/2015 2:55:15 PM	TEXAS INSTRUMENTS	

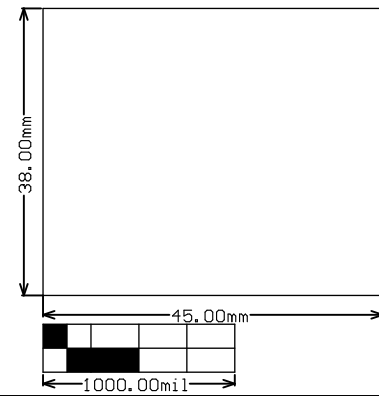


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11302	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 10/7/2015 2:55:16 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	6	10.00mil (0.254mm)	PTH	Round
○	2	33.00mil (0.838mm)	PTH	Round
▽	2	37.40mil (0.950mm)	PTH	Round
✱	8	39.37mil (1.000mm)	PTH	Round
✱	6	40.00mil (1.016mm)	PTH	Round
✱	2	62.99mil (1.600mm)	PTH	Round
	26 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11302	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 10/7/2015	2:55:16 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11302	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 10/7/2015 2:55:17 PM	TEXAS INSTRUMENTS	



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